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09/899,957	07/06/2001	James W. Adkisson	FIS920010105US1	4378
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	CURTIS & CHRIST	EXAMINER		
SUITE 340	ET HILLS ROAD	TRINH, MICHAEL MANH		
RESTON, VA	A 20190			
			ART UNIT	PAPER NUMBER
			2822	
			DATE MAILED: 03/28/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

		A tio ati m A	Applicant(s)	Me			
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		09/899,957	ADKISSON ET A	L.			
	Offic Action Summary	Examiner	Art Unit				
		Michael Trinh	2822				
The MAILING DATE f this communication appears on the cover sheet with the correspondence address Period for Reply							
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). Status							
1)[🛛	Responsive to communication(s) filed on <u>08</u>	January 2003					
2a)⊠	This action is FINAL . 2b) ☐ T	his action is non-fina					
3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213. Disposition of Claims							
4) 🖂	Claim(s) 12-21 is/are pending in the application	ion.					
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5)	5) Claim(s) is/are allowed.						
6)⊠	☑ Claim(s) <u>12-21</u> is/are rejected.						
7)	7) Claim(s) is/are objected to.						
8)	8) Claim(s) are subject to restriction and/or election requirement.						
Application Papers							
9) The specification is objected to by the Examiner.							
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.							
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.							
If approved, corrected drawings are required in reply to this Office action.							
12) The oath or declaration is objected to by the Examiner.							
Priority under 35 U.S.C. §§ 119 and 120							
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).							
a)	☐ All b)☐ Some * c)☐ None of:						
	1. Certified copies of the priority documen						
	2. Certified copies of the priority documents have been received in Application No						
* 5	 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
	acknowledgment is made of a claim for domes			al application).			
a) ☐ The translation of the foreign language provisional application has been received. 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.							
Attachmen		processing among the					
1) Notice 2) Notice 3) Inform	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449) Paper No(s)	5) 🔲 No	erview Summary (PTO-413) Paper No stice of Informal Patent Application (PT ner:				
U.S. Patent and T PTO-326 (Re		Action Summary	Part	of Paper No. 8			

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DETAILED ACTION

- *** This office action is in response to Applicant's election filed on January 08, 2003. Claims 12-21 are currently pending. Claims 1-11 and 22 were canceled.
- *** The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
- ** In claim 17, "said gate" should be --said gate structure-- for proper antecedent basis.

Claim Rejections - 35 USC § 112

1. Claims 12-21 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Re claim 12, meaning and scope of "precisely desired location" are unclear and indefinite for how much "precisely desired" is it?.

Re claims 15-16, since claim 1 already recites "an insulator layer", using the same term of "an insulator layer" in claims 15-16 for different film renders meaning and scope of the claim being unclear and indefinite.

Re claim 1, meaning of "substantially free..." is a relative term which renders the claim indefinite. The term "substantially free..." is not defined by the claim, the specification does not provide a standard for ascertaining the requisite degree, and one of ordinary skill in the art would not be reasonably apprised of the scope of the invention.

Re claims 1,13,15-16, and 20-21: Meaning and scope of the claims are unclear, contradictory and indefinite. For examples, Claim 13 recites "the dielectric layer have been removed" whereas the product base claim 1 includes the dielectric layer having a trench. Similarly, product base claim 15 recites "an insulator layer deposited over... said gate structure" while product claim 16 differently recites "... the insulator layer is planarized to said gate structure" (thus not deposited over). Product claims 20-21 recite "a sidewall within said trench". However, the sidewall is not remained with the gate structure. As shown in Figures 9-10 and described in the specification, the diffusion source sidewall is removed after diffusion. (Other dependent claims are rejected as depending on rejected base claim)

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Insofar as understood, art rejections are applied as follows:

Claim Rejections - 35 USC § 102

2. Claims 12-14,17-21 are rejected under 35 U.S.C. 102(b) as being anticipated by Nowak et al (6,528,846).

Nowak teaches an asymmetric field effect transistor comprising: a semiconductor layer 7 formed on an insulator layer 2, wherein the semiconductor layer 7 including impurities supplied thereto and adjacent source and drain regions 39,41 (Figs 1D-1G), wherein the impurities in regions 21,31,24,23 have a precisely desired location in portions of the semiconductor layer, and located at edges of a trench formed by the dielectric layer 35, and a gate structure 15 formed on a portion of the semiconductor layer in the trench formed by the dielectric layer 35 with asymmetrical diode properties at the source and drain regions 39,41, wherein the transistor is substantially free floating body effect due to the electrical connection between the source and the floating body (col 1, lines 15-20; col 3, lines 20-26, lines 45-50). Re claims 13 and 17, wherein source and drain regions 39,41 are formed adjacent to the gate structure 15, and wherein there is no dielectric layer thereon (Fig 1G). Re claim 18, wherein the gate structure 15 is planarized to the dielectric layer 35. Re claims 14, 19, 20, and 21, Re further claims 12-21, the claims are directed to the product per se, no matter how actually made by process limitations including "implanting", "diffusion" from "a sidewall within", "angled implantation", "planarizing", "removing", etc..

A "product by process" claim is directed to the product per se, no matter how actually made, *In re Hirao*, 190 USPQ 15 at 17 (footnote 3). See also In re Brown, 173 USPQ 685; In re Luck, 177 USPQ 523; In re Fessmann, 180 USPQ 324; In re Avery, 186 USPQ 161; In re Wertheim, 191 USPQ 90 (209 USPQ 554 does not deal with this issue); In re Marosi et al, 218 USPQ 289; and particularly In re Thorpe, 227 USPQ 964, all of which make it clear that it is the patentability of the final product per se which must be determined in a "product by process" claim, and not the patentability of the process, and that an old or obvious product produced by a new method is not patentable as a product, whether claimed in "product by process" claims or not.

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3. Claims 12-14,17,19-21 are rejected under 35 U.S.C. 102(b) as being anticipated by Long et al (6,525,381).

Long et al teach an asymmetric field effect transistor comprising: a semiconductor layer (e.g. 14 in Fig 2, col 4, line 45 through col 5; or 114 in Figs 8-11; col 6, line 54 through col 8) formed on an insulator layer 16 (Fig 2), wherein the semiconductor layer 14 including impurities supplied thereto and adjacent source and drain regions 20,22, wherein the impurities have a precisely desired location in portions of the semiconductor layer, and a gate structure 48 formed on a portion of the semiconductor layer with asymmetrical diode properties at the source and drain regions 20,22 (Fig 2; col 1, lines 60-65), wherein the transistor is formed to avoid of floating body effect (col 1, lines 10-13), wherein the floating body effect is substantially avoid and free due to the electrical coupling between the source and the floating body (col 1, lines 1-13,40-50). Re claims 13 and 17, wherein source and drain regions 20,22 are formed adjacent to the gate structure 48, and wherein there is no dielectric layer thereon (Fig 2). Re further claims 12-14,17,19-21, the claims are directed to the product per se, no matter how actually made by process limitations including "implanting", "diffusion" from "a sidewall within", "angled implantation", "planarizing", "removing", etc..

A "product by process" claim is directed to the product per se, no matter how actually made, *In re Hirao*, 190 USPQ 15 at 17 (footnote 3). See also In re Brown, 173 USPQ 685; In re Luck, 177 USPQ 523; In re Fessmann, 180 USPQ 324; In re Avery, 186 USPQ 161; In re Wertheim, 191 USPQ 90 (209 USPQ 554 does not deal with this issue); In re Marosi et al, 218 USPQ 289; and particularly In re Thorpe, 227 USPQ 964, all of which make it clear that it is the patentability of the final product per se which must be determined in a "product by process" claim, and not the patentability of the process, and that an old or obvious product produced by a new method is not patentable as a product, whether claimed in "product by process" claims or not.

Claim Rejections - 35 USC § 103

4. Claims 15-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nowak et al (6,528,846) taken with Lee (6,214,677).

Nowak teaches an asymmetric field effect transistor as applied to claims 12-14,17-21 above.

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Re claims 15-16, Nowak lacks to form a planarized insulator layer to the gate structure 213 as shown in Figure 4D.

However, Lee teaches (at col 3, lines 47-68; Figs 1C-1D) that after forming source and drain regions 122, deposit an oxide insulator layer and planarized to form the planarized oxide insulator layer 124 with the gate structure 116a (Fig 1D).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to form the transistor of Nowak by forming a planarized insulator layer on the gate structure as taught by Lee. This is because of the desirability to form a planar device structure, to protect the underlying structure, and to form an interlayer insulator for subsequent electrical connection.

5. Claims 15-16,18 are rejected under 35 U.S.C. 103(a) as being unpatentable over Long et al (6,525,381) taken with Lee (6,214,677).

Long et al teach an asymmetric field effect transistor as applied to claims 12-14,17,19-21 above.

Re claims 15-16, Long et al lack to form a planarized insulator layer to the gate structure 213 as shown in Figure 4D. Re claim 18, the gate structure is planarized to the dielectric layer.

However, Lee teaches (at col 3, lines 47-68; Figs 1C-1D) that after forming source and drain regions 122, deposit an oxide insulator layer and planarized to form the planarized oxide insulator layer 124 with the gate structure 116a (Fig 1D). In another words, Lee teaches (at col 3, lines 47-68; Figs 1C-1D) depositing and planarizing an oxide dielectric layer to form a planarized oxide dielectric layer 124 so that the gate structure 116a is planarized with the dielectric layer 124 (Fig 1D).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to form the transistor of Long by forming a planarized insulator layer or dielectric layer adjacent to the gate structure as taught by Lee. This is because of the desirability to form a planar device structure, to protect the underlying structure, and to form an interlayer insulator or dielectric layer for subsequent electrical connection.

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6. Claims 20-21 are further rejected under 35 U.S.C. 103(a) as being unpatentable over Nowak et al (6,528,846) or Long et al (6,525,381) taken with Chau et al (5,434,093).

Nowak or Long teaches an asymmetric field effect transistor formed on a semiconductor substrate as applied to claims 12-14,17-19 above.

Nowak or Long teaches forming a doped region by implantation impurities, but lacks forming a sidewall of a doped material for diffusing impurities as recited in claims 20-21.

It is maintained that the claims are directed to the product per se, no matter how actually made by process limitations including impurities have been supplied by diffusion from the sidewall within the trench, In re Thorpe, 227 USPQ 964. Chau is however cited to show (at col 14, line 60 through col 15, line 30; Figs 5a-5d) a doped region 503b formed by diffusing impurities from a sidewall 510b of a doped material.

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to form the transistor having the doped region of Nowak or Long by diffusing impurities from the sidewall of a doped material as taught by Chau, because these techniques are alternative and equivalent for substitution in order to the doped region at the edge of the gate structure.

Response to Arguments

- 7. Applicant's amendment and remarks filed January 08, 2003 have been fully considered but they are most in view of the new ground(s) of rejection.
- ** The relied references including Nowak '846 and Long '381 are directed to an SOI transistor having asymmetric diode properties at the source and drain regions, wherein floating body effect is sought to be substantially avoided or free.

It is noted that the claims are still involved to "product by process" claim. However, the claims are directed to the product per se, no matter how actually made by process limitations including "implanting", "diffusion" from "a sidewall within", "angled implantation", "planarizing", "removing", etc.. A "product by process" claim is directed to the product per se, no matter how actually made, *In re Hirao*, 190 USPQ 15 at 17 (footnote 3). See also In re Brown, 173 USPQ 685; In re Luck, 177 USPQ 523; In re Fessmann, 180 USPQ 324; In re Avery, 186 USPQ 161; In re Wertheim, 191 USPQ 90 (209 USPQ 554 does not deal with this

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issue); In re Marosi et al, 218 USPQ 289; and particularly In re Thorpe, 227 USPQ 964, all of which make it clear that it is the patentability of the final product per se which must be determined in a "product by process" claim, and not the patentability of the process, and that an old or obvious product produced by a new method is not patentable as a product, whether claimed in "product by process" claims or not.

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michael M. Trinh whose telephone number is (703) 308-2554. The examiner can normally be reached on M-F from 8:30 Am to 4:30 Pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (703) 308-4905. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7724 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

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Michael Trinh Primary Examiner